



#### IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re: Application of:

Scott Jessen, et al.

Group Art Unit: 2822

Examiner: Maria F. Guerrero Telinology CENTER 28

Serial No.: 09/966,157

Filed: 09/28/2001

Title: MASK LAYER AND INTERCONNECT

STRUCTURE FOR DUAL DAMASCENE SEMICONDUCTOR MANUFACTURING

Commissioner for Patents Box Fee Amendment Washington, DC 20231

## RESPONSE

The paper is submitted in response to the Office Action mailed June 6, 2002, for which a response was due by July 6, 2002.

# RESTRICTION

The Applicant herein responds to the restriction requirement in the abovereference Office Action wherein the Applicant restricts the application to claims 6 through 20 for the purpose of examination. Applicant makes this restriction with traversal, which is set forth in detail in the below Remarks.

## **AMENDMENT**

Please add the following claims:

21. (Added) A method for the fabrication of a semiconductor device including a wafer substrate having a dielectric material formed over a metallization layer formed over said wafer substrate, comprising the steps of:

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